

RESPONSE TO RESTRICTION REQUIREMENT AND AMENDMENT
U.S. Application No: 10/026,454

Q1 6. (amended) A wiring substrate comprising: a core substrate; and a build-up layer provided on at least one side of the core substrate and formed by alternately laminating an insulating layer and a wiring layer, wherein at least one of the core substrate and the building-up layer has an opening penetrating therethrough, and an electronic part is disposed in the opening and embedded with an embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than $85 \text{ Pa} \cdot \text{s}$ in a shear rate of 8.4 s^{-1} after being allowed to stand for 24 hours at $25^{\circ}\text{C} \pm 1^{\circ}\text{C}$.

Claims 7, 8, 9, 10, 11 and 12 are added as new claims.

sub B1 7. The embedding resin according to claim 5, wherein the acid anhydride curing agent has a viscosity at $25^{\circ}\text{C} \pm 1^{\circ}\text{C}$ of not higher than $170 \text{ mPa} \cdot \text{s}$.

G2 8. The embedding resin according to claim 5, which contains the filler in an amount of from 51% by weight to 74% by weight.

sub B2 9. The embedding resin according to claim 5, wherein the filler contains at least one inorganic filler.

10. The embedding resin according to claim 6, wherein the acid anhydride curing agent has a viscosity at $25^{\circ}\text{C} \pm 1^{\circ}\text{C}$ of not higher than $170 \text{ mPa} \cdot \text{s}$.

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11. The embedding resin according to claim 6, which contains the filler in an amount of
from 51% by weight to 74% by weight.

12. The embedding resin according to claim 6, wherein the filler contains at least one
inorganic filler.